



Adhesives for Electronic Assembly

PARLITE UV/Visible Curable Adhesives

PARTITE Methacrylate Adhesives

PARBOND Epoxy Adhesives

PARLITE® UV/ Visible Cure Adhesives for Electronic Application

Parson offers wide range of UV, Visible and Multi-Cure adhesives for variety of electronic applications for bonding, potting, encapsulating, coating, tacking and sealing. Parson's state-of-the-art research and development facility offers custom formulations to meet customer's specifications and performance requirement. This brochure describes some of our most popular grades but there are many other grades available which are not listed here. These products are available in wide variety of packing such as syringe, bottle, and drum.

Conformal Coatings for Protection of Electronic Circuit Board

Grade	Substrates	Viscosity @ 25°C cps	Shore Hardness	Modulus of Elasticity psi	Dielectric Strength volts/mil	Application
4750	PCB Boards, Glass-Filled Epoxy, Ceramic, Metals	150 - 200	D80 - D85	60,000 - 70,000	1,700 - 1,900	Tough, glossy conformal coating with excellent adhesion to variety of PC boards and masks. Multi-cure with fast speed.
4753	Glass-Filled Epoxy, PCB Boards, Metals	2,200 - 2,500	D60 - D65	12,000 - 15,000	> 1,500	Medium viscosity; Multi-cure coating for wetting components, low modulus for enhanced thermal cycling performance.

Chip Encapsulants & Wire Bonders

Parlite line of encapsulants offers superior protection to flexible and rigid platforms. These high performance encapsulants are 100% solvent free, electrically insulating, offers excellent thermal and moisture resistance.

Grade	Substrates	Viscosity @ 25°C cps	Shore Hardness	Elongation at Break %	Modulus of Elasticity psi	Color	Application
4713	PET, Polyimide, Metals	4,000 - 5,000	D45 - D50	140 - 160	2,500 - 3,000	Clear	Ideal for Chip on Board, Chip on Flex, Chip on Glass, Wire bonding, Bare-die encapsulation.
4716	PET, Polyimide, Metals, Glass	15,000 - 20,000	D45 - D50	140 - 160	2,500 - 3,000	Clear	Higher viscosity version of Parlite 4713. Low modulus for wire bonding application.

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Display Bonding & Laminating

PARSON manufactures wide range of UV/Visible cure adhesives for optical display bonding and laminating applications such as touch panel assembly including bonding flat panel displays, touch screens, LCD screens, tablets, outdoor kiosks, navigation systems, liquid crystal displays, kiosk panels, mobile phones, and smart connected devices.

Grade	Substrates	Viscosity @ 25°C cps	Color	Refractive Index	Tensile Strength	Hardness	Application
4721	Glass, LCD, Plastics	10,000 - 12,000 cps	Clear	1.507	900 - 1,200 psi	60D - 62D	LCD End-sealing, Bonding frame to display surface, Bonding components.
4723	Glass, LCD, Plastics	900 - 1,100 cps	Clear	1.497	700 - 950 psi	68D - 70D	Optical display lamination. Touch screen assembly.

Micro-Speaker Assembly Adhesives

PARLITE range of adhesives cures in seconds to offer optimum performance for micro-speaker assembly including bonding, sealing and wire-fixing. These adhesives designed to improve quality of sounds and easy of production.

Grade	Substrates	Viscosity @ 25°C cps	Color	Tensile Strength psi	Elongation %	Shore Hardness	Application
4731	Plastics	400 - 500 cps	Clear	2,300 - 2,500	85 - 95	54D - 58D	Speaker assembly, plastic housing assembly, flexible plastic lamination, appliance assembly.
4733	Plastics	40,000 - 50,00 cps	Red	2,000 - 2,200	70 - 80	54D - 56D	Micro-speaker membranes to housings, LCP bonding.
4734	Metals, Plastics	60,000 - 80,00 cps	Red	2,100 - 2,300	110 - 120	50D - 52D	Wire-Fixing, Contact sealing, Bonding coil to membrane in speaker assembly.

Smart Card, Dam & Fill Encapsulant

PARLITE offers UV curable encapsulant based on epoxy system for smart card technology to fill dam & fill.

Grade	Substrates	Viscosity @ 25°C cps	Shore Hardness	Volume Shrinkage	Elongation	Color	Application
4741	Plastics	4,500 - 5,200 cps	78D - 80D	2 - 3 %	5 - 8 %	Transparent	Speaker assembly, plastic housing assembly, flexible plastic lamination, appliance assembly.
4743	Plastics	160,000 - 190,000 cps	60D - 62D	2 - 3 %	18 - 22 %	Transparent	Encapsulant for smart card technology. Dam for Dam & Fill.

Epoxy Adhesives for Electronic Assembly

Parbond Grade	Substrates	Viscosity @ 25°C cps	Specific Gravity	Tensile Strength psi	Cure Mechanism	Hardness	Application
5717	Glass Epoxy	2,400 - 3,000 cps	1.36	1,800 - 2,100	30 minutes @ 80° C	78D - 80D	One component epoxy adhesive. Ideal for heat sensitive devices such as image sensors and MMC.
5720	Metals, Ceramic	30,000 - 34,000 cps	1.51	2,000 - 2,200	15 seconds @ 150° C	82D - 84D	Flip-chip applications on aluminum antennas.
5150	Metals, Ceramic, Glass-filled epoxy, Plastics	17,000 - 22,000 cps	1.15	2,100 - 2,300	5 minutes @ RT	72D - 75D	Two component system. Wide variety of electronic assembly.

Structural Adhesives for Electronic Assembly

Partite Grade	Substrates	Working Time Minutes	Fixture Time Minutes	Tensile Elongation %	Shear Strength psi	Mix Ratio	Application
7419	Metals, Plastics, Composites	2 - 4	6 - 9	50 - 70	2,100 - 2,300	10:1	Two part structural adhesive for variety of electronic assembly. Fast cure speed.
5720	Metals, Plastics, Composites	4 - 6	12 - 15	20 - 30	3,200 - 3,750	1:1	Ideal for electronic enclosure application. Easy to use with fast cure speed.



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